Special Issue

Industry 4.0 Based Smart Manufacturing Systems

Message from the Guest Editor

In a traditional way, manufacturing means the engineering process of creating industrial products from raw materials using a variety of subtractive and additive methods. However, in recent years, the concept of manufacturing has drastically shifted.After the first wave of digitization, new and modernized technologies such as integrated sensors, advanced robotics, and artificial intelligence led to the so-called Smart Manufacturing as part of the fourth industrial revolution—often referred to as Industry 4.0. In Smart Manufacturing, production tools are connected to constantly gather data, monitor production processes, and perform real-time optimization. Smart Manufacturing therefore includes not only data collection and processing, but also inferring from and reasoning about data by means of cognitive computing to improve the end product. The aim of the edition "Industry 4.0-Based Smart Manufacturing Systems" is therefore to present new and innovative methods in which data can be better and more efficiently extracted, collected, processed, and finally used in Smart Manufacturing environments.

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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